

ABSTRACT OF THE DISCLOSURE

An adapter for a surface mount device, the adapter including an insulating body having offset first and second surfaces; a pattern of surface mount solder pads formed on the first surface; a pattern of signal carriers communicating between the first and second surfaces, each of the signal carriers being at least partially exposed in an area between the first and second surfaces and adjacent to the second surface; and a plurality of signal lines electrically coupling one or more of the surface mount solder pads with predetermined ones of the signal carriers.

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